

# Hirose Korea LCD Interface Connector

## **KN10G-30S-1H**

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# KN10G-30S-1H



## ■ FEATURES

1. This connector is a LCD interface conndctor. And it's supplied in embossed tape allowing automated mounting.  
This connector might use any display of Note PC, Monitor, TV etc.
2. This connector is covered with metallic shell. So it is stabilized after reflow for SMT.
3. It's possible to transmit high differential transmission.
4. It's a Pb-free product comply with environmental regulations.

## ■ APPLICATIONS

**LCD DISPLAY of NOTE, MONITOR, TV etc.**

## ■ MATERIAL

PART		MATERIAL	REMARK
RESEPTACLE	INSULATOR(CASE)	POLYAMIDE	UL94V-0 / BEIGE
	CONTACT	Phosphor Bonze	NiP+AuP / SnP
	GROUND PLATE	Phosphor Bonze	SnP
	SHELL	STAINLESS STEEL	NiP

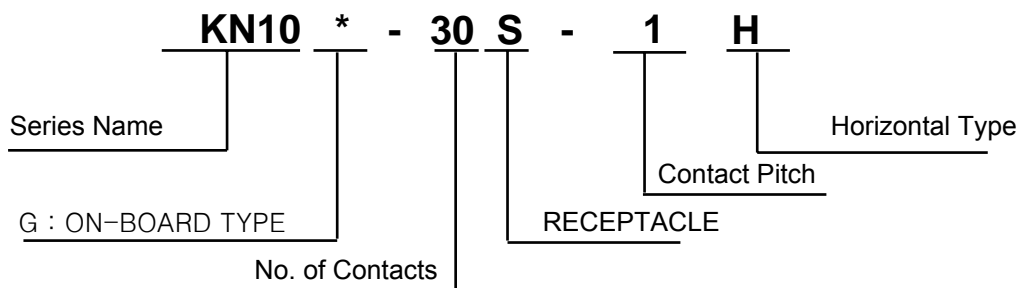
## ■ Specifications

Rating	Current 1A AC, DC	Operating temperature range	Storage temperature range
	Voltage 200V AC	- 40 °C ~ + 80 °C	- 10 °C ~ + 60 °C

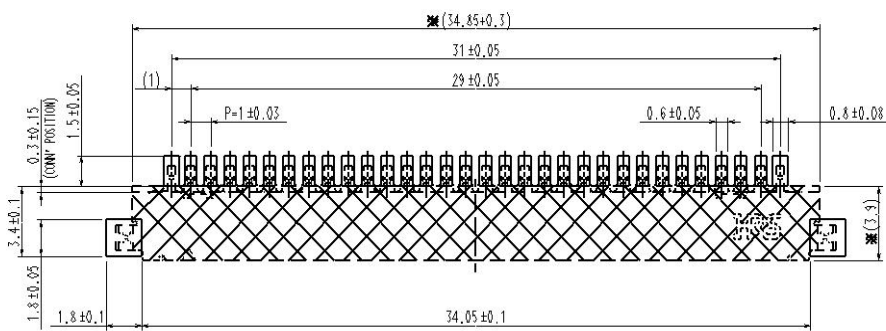
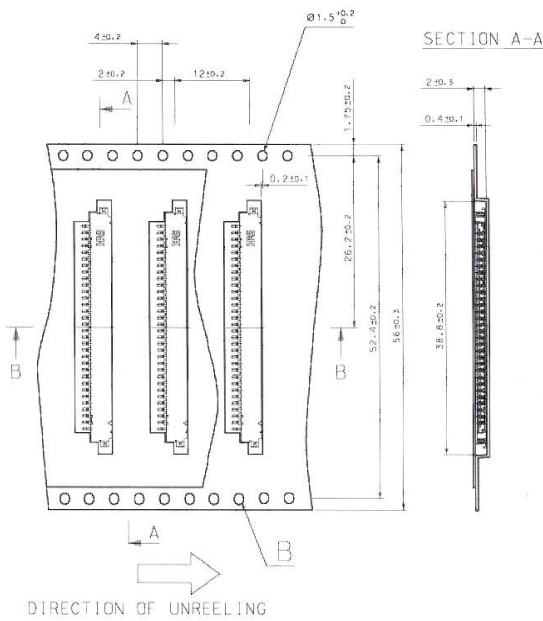
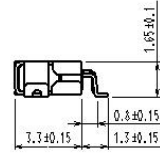
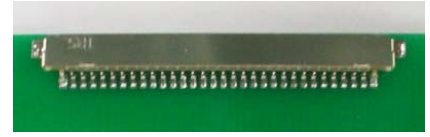
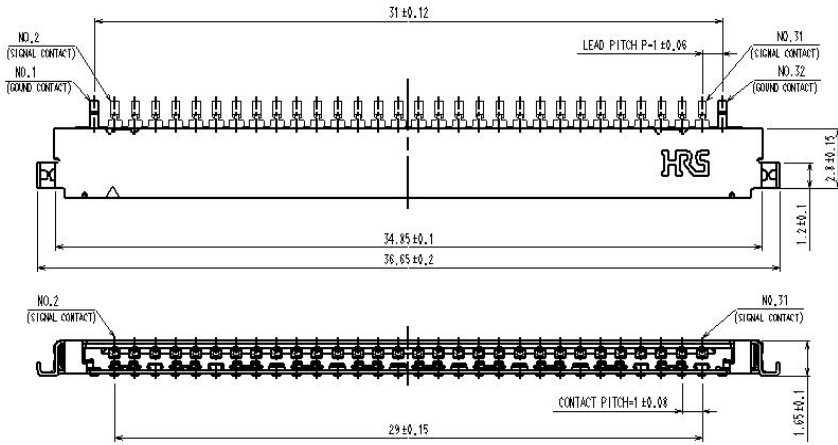
  

Item	Specification	Condition
1.Insulation Resistance	100MΩ Min	Measured at 100V DC
2.Withstand voltage	Neither shot or insulation beakdown	200V AC for 1 minute
3.Contact Resistance	40mΩ Max	Measured at 100mA
4.Mechanical operation	Contact Resistance : 80mΩ Max	50 Time insertions and extractions.
5.Moisture Resistance	Temperature : 60±2°C	Contact Resistance : 80mΩ Max Insulation Resistance : 50MΩ Min
	Relative Humidity : 90~95%	
	Duration : 96Hr	

## ■ Formation of part number.



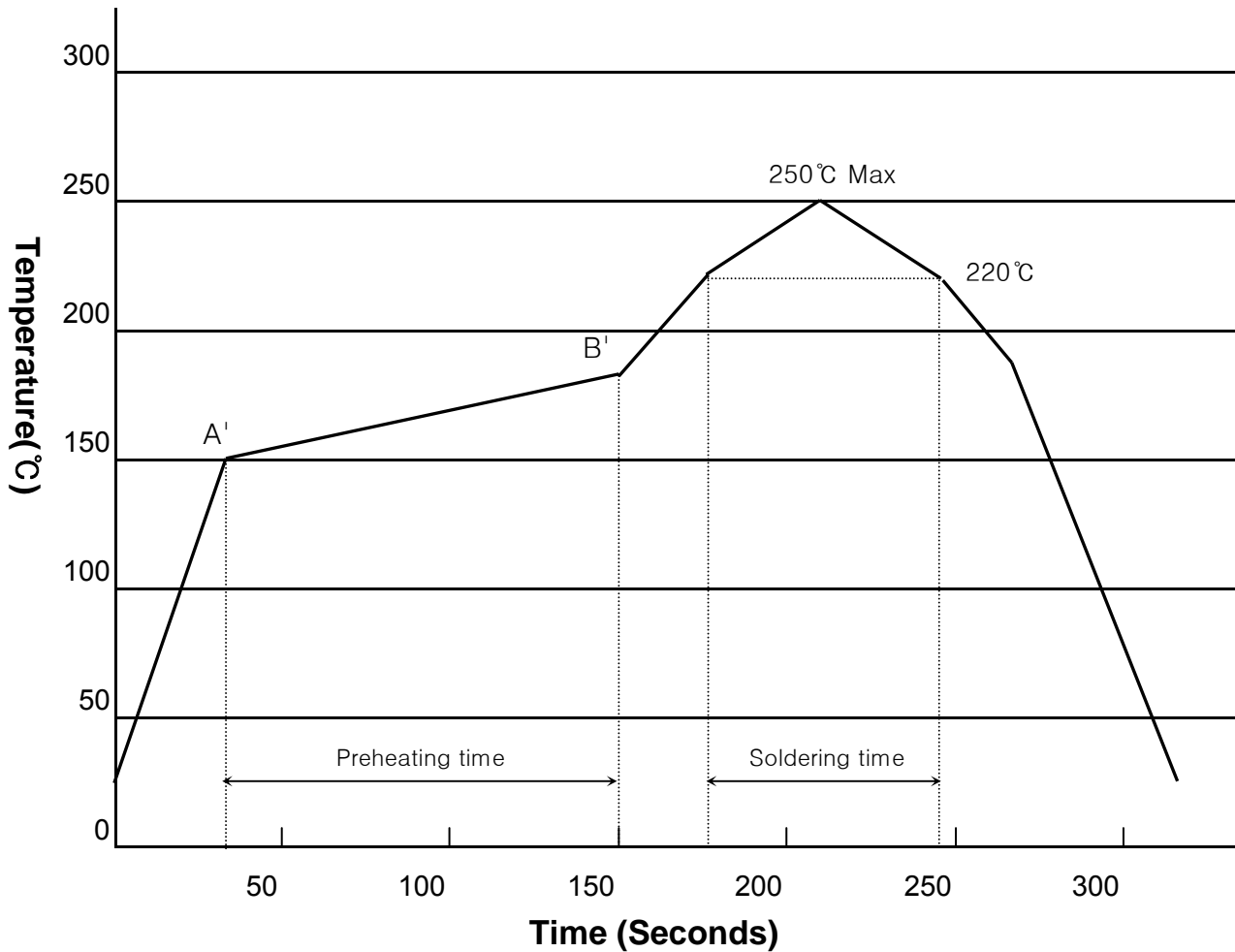
# KN10G-30S-1H



Product Name	PITCH	Package	Remark
KN10G-30S-1H	1mm	Emboss Tape	2,000ea/Reel

## ■ Reflow Profile

Using Lead-free Solder Paste



### Recommended Application Conditions

Reflow System: IR reflow

Solder: Cream type Sn / 3 Ag / 0.5 Cu

Flux content 11%wt

Metal mask thickness: 0.15mm

Preheating time: 150°C~190°C, 90±30seconds

A'=150°C~170°C, B'=170°C~190°C

Soldering time: 250°C Max

220°C Min, 30~60 seconds